



Timing at Belle-II Vertex Detector (VXD)

Yitong Liu

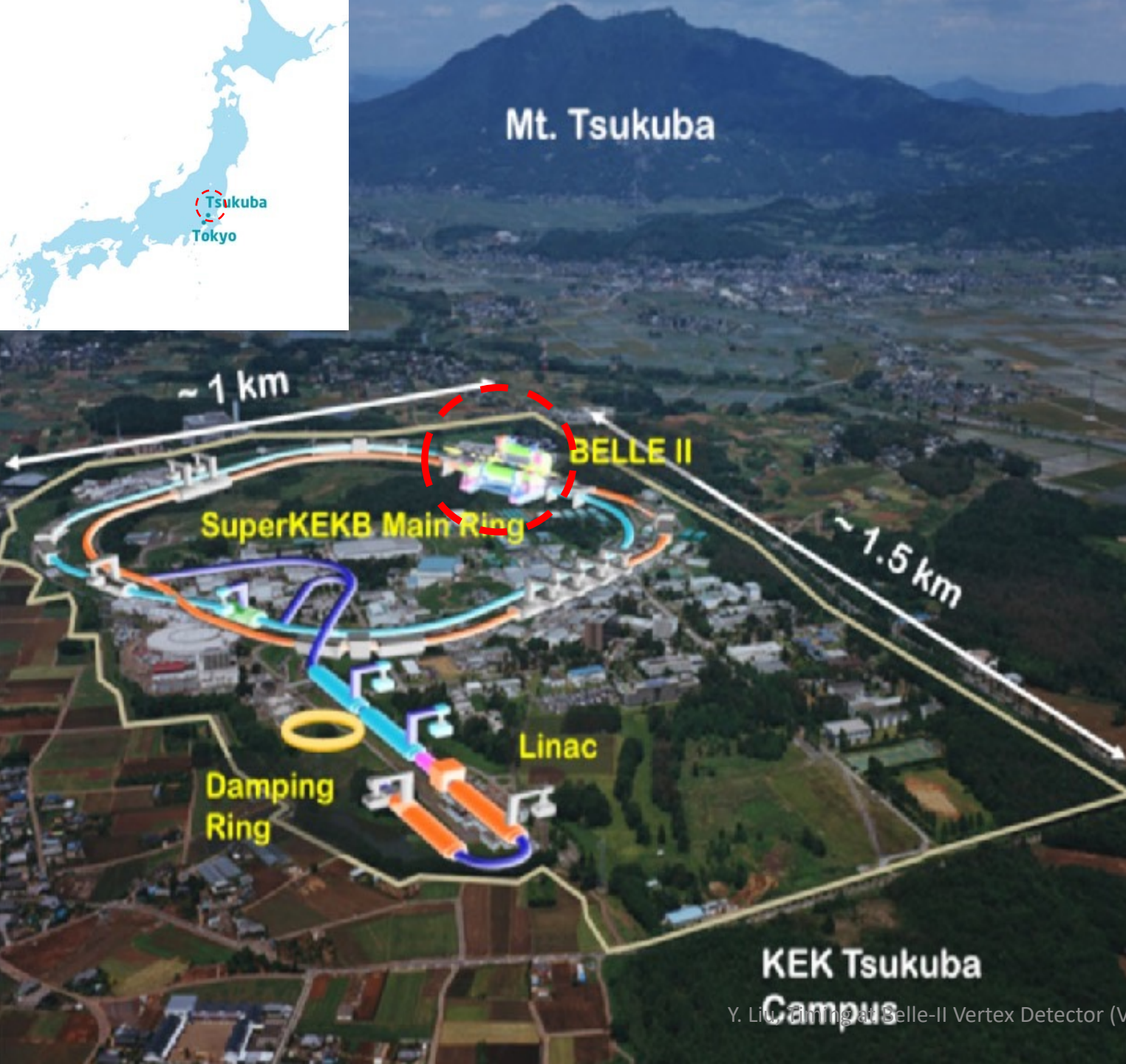
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PSA M2 Defense 22/06/2023



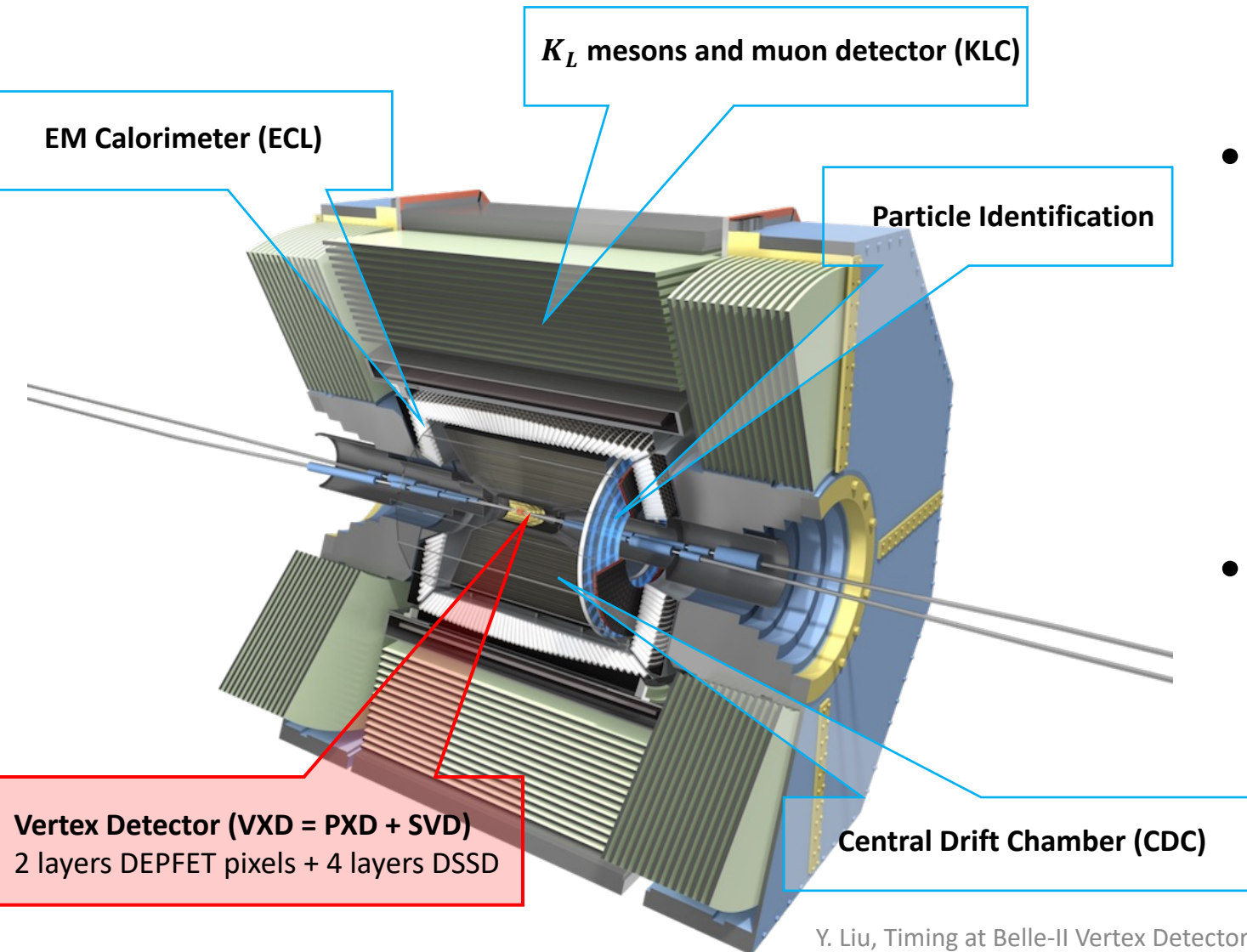
Mt. Tsukuba



SuperKEKB is an e^-e^+ collider:

- Asymmetric energy:
 - $7\text{GeV } e^- + 4\text{GeV } e^+$
- Center of mass energy:
 10.5 GeV
- Bunch crossing: **4 ns**
 - **Continuous background**
- Luminosity goal:
 $6 \times 10^{35} \text{ cm}^{-2} \text{ s}^{-1}$
- Rare events & high precision

Belle-II detector



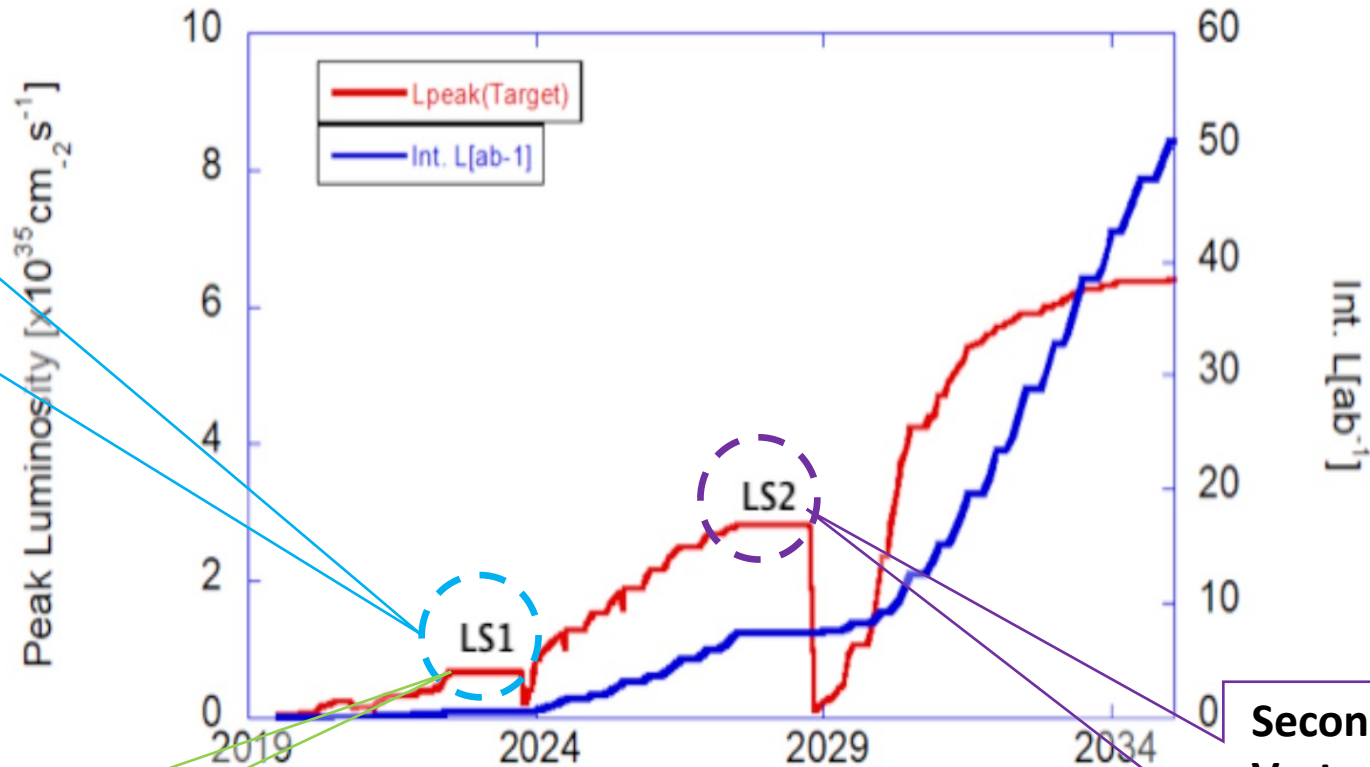
- **Silicon Vertex Detector (SVD):**

- 4 outer layers of the VXD
 - Strip detectors
-
- Track reconstruction for low momentum charged particles & decay vertex reconstructions

Timing strategies to high-luminosity conditions

First long shut down
(currently):

Lighter data format for
bandwidth reduction (reaching
3% occupancy limit)



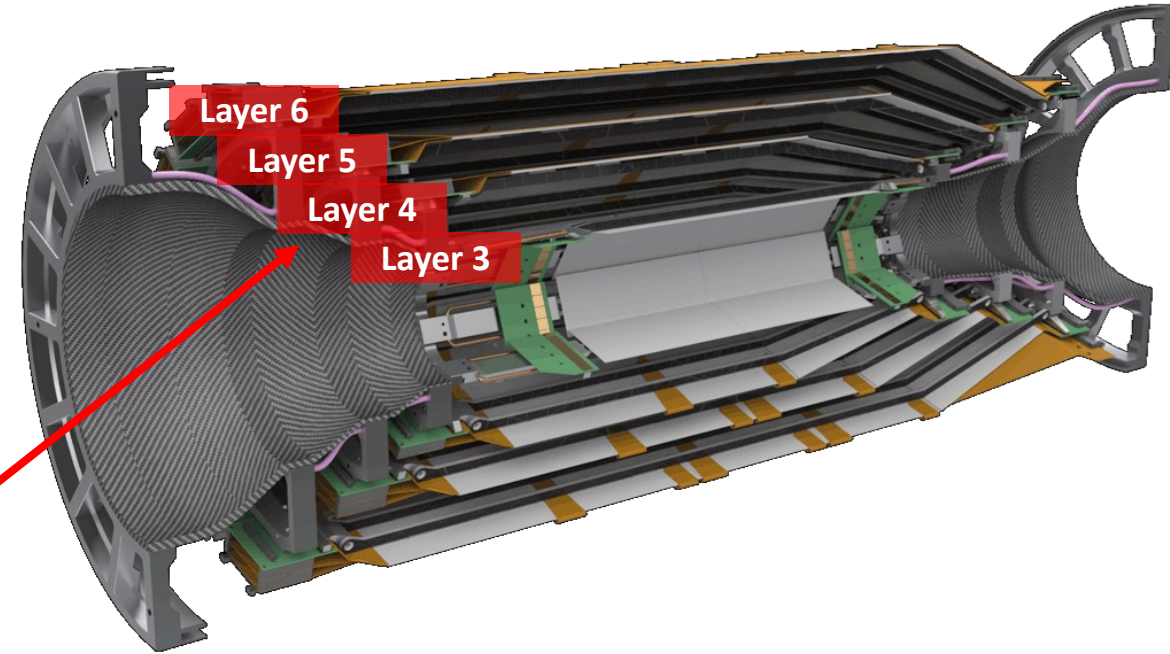
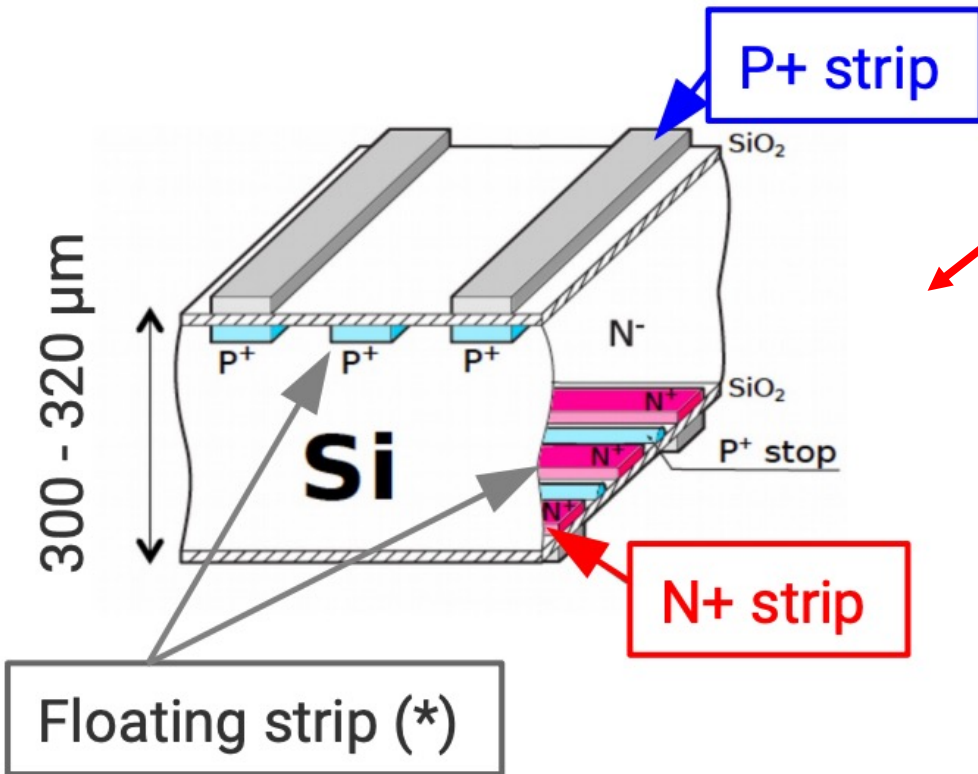
Second long shut down (~2027):
Vertex Detector (VTX) upgrades
using pixel sensors to lower
occupancy
→ Finer space and time
granularity

2 long shut downs/upgrades

Highest peak luminosity
recorded in 2022:
 $4.7 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$

SVD strip silicon sensors

Double-Sided Strip Detector (DSSD)

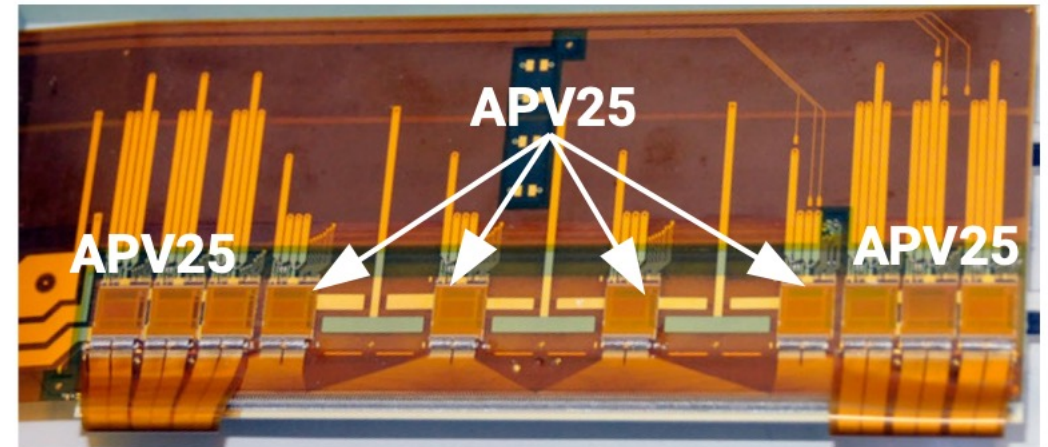


- **Signal generated by the drifted charge in the sensor:**
 - ~ 24000 e/h pairs
- **Layer 3:**
 - Strip pitch : $50(p) \times 160(n)$ μm
 - # strips : $768(p) \times 768(n)$

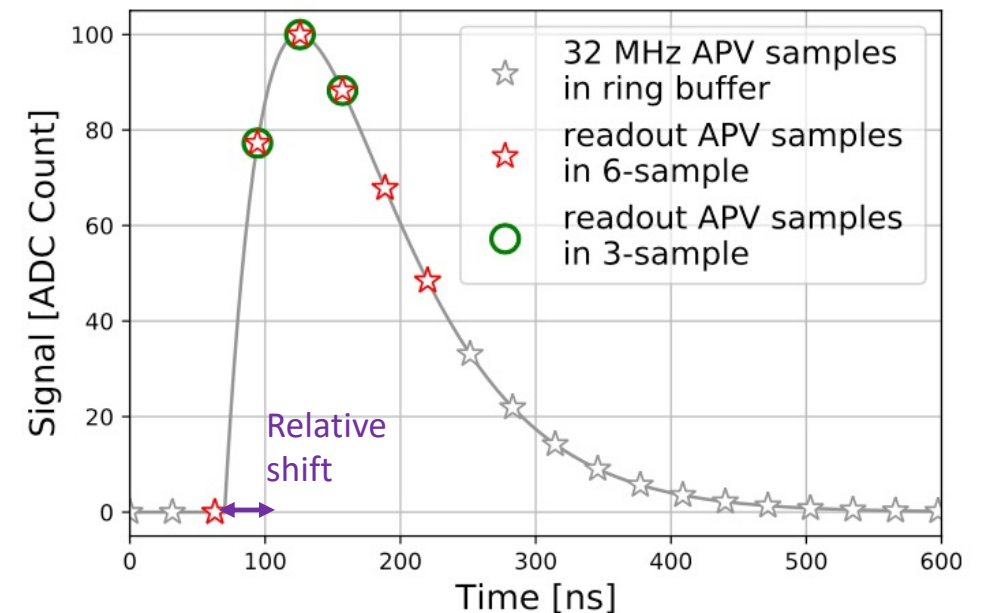
Readout system: APV 25

- **APV 25 is connected to the strip sensor for signal readout:**
 - Clock frequency: ~ 32 MHz
- After a trigger is specified, the chip will go back in time to search for the samples in the buffer that match the trigger
- **Currently, 6-sample mode is being used:**
 - 3-sample is emulated from the 6-sample by doing a **relative shift**

Readout front-end on a sensor



APV 25 readout



SVD cluster time reconstruction

- **Sum APV outputs:** 3 best summed consecutive samples
- **Two main algorithms** for $t_{cluster}$ reconstruction:
 - **CoG3:** center of gravity

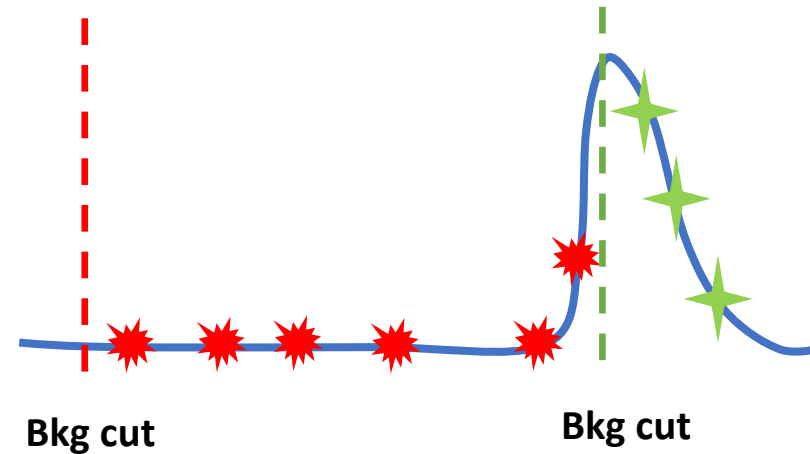
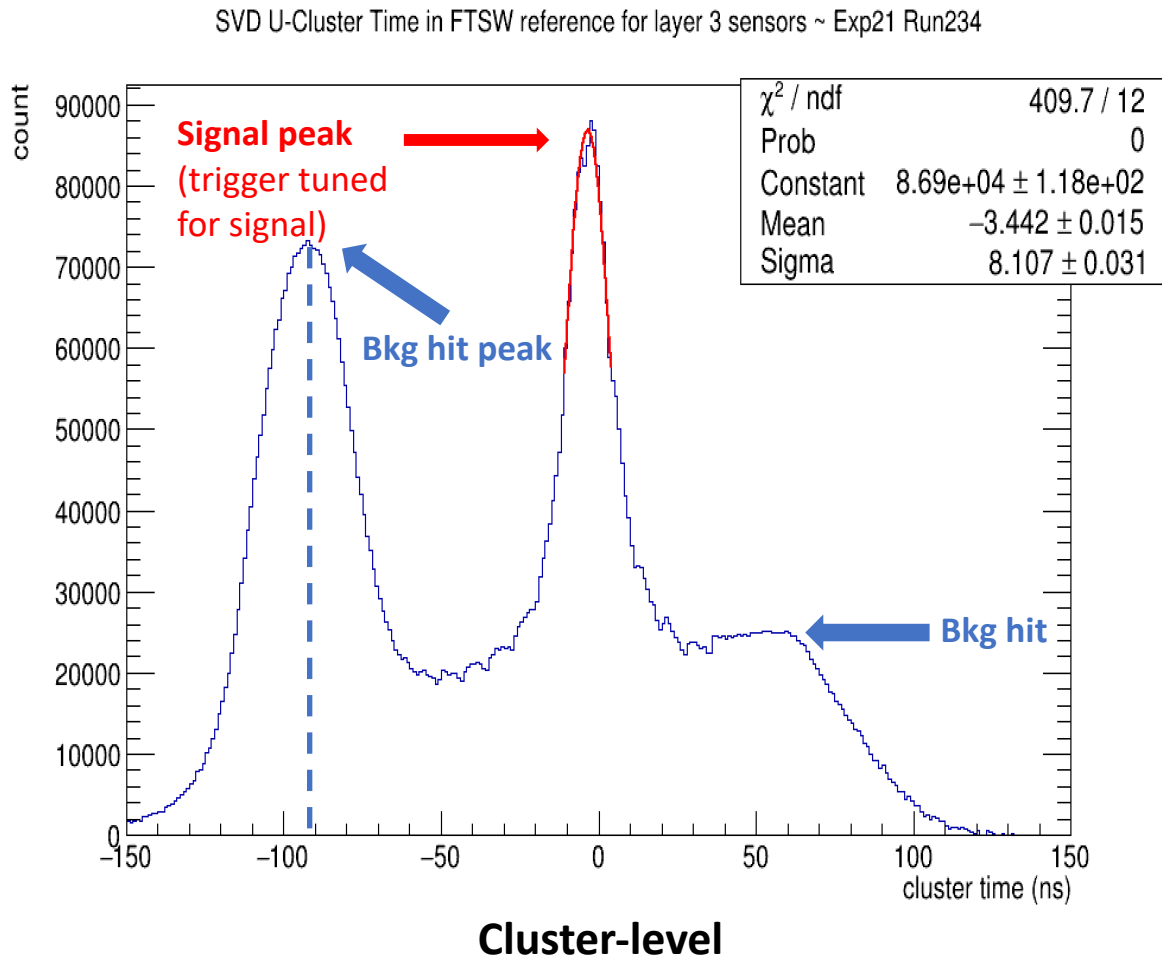
$$T_{SVD;raw} = \frac{\sum_{i=0}^2 a_i \cdot i\Delta t}{\sum_{i=0}^2 a_i}.$$

- **ELS3:** approximate pulse shape + least square

$$a(t) = A \frac{t - T_{SVD;raw}}{\tau} \exp\left(1 - \frac{t - T_{SVD;raw}}{\tau}\right)$$

- Currently, **CoG3 is the default**
- However, ELS3 might be better for high luminosity

SVD 6-sample CoG3 cluster time

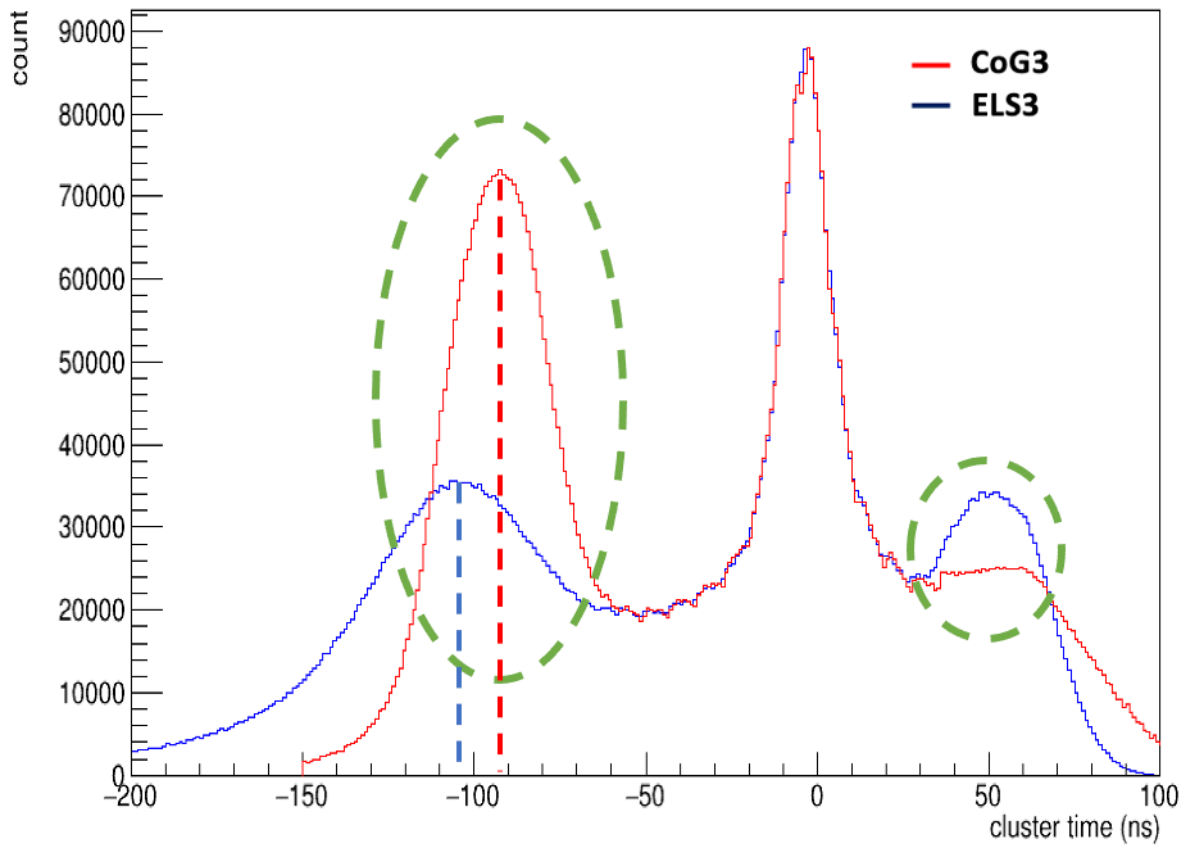


- The background arrival time is not synchronous to the trigger time.
- **The distorted bkg time estimation leads to the bkg hit peak**

SVD algorithm comparison

Hard to tell which algorithm performs better in background rejection

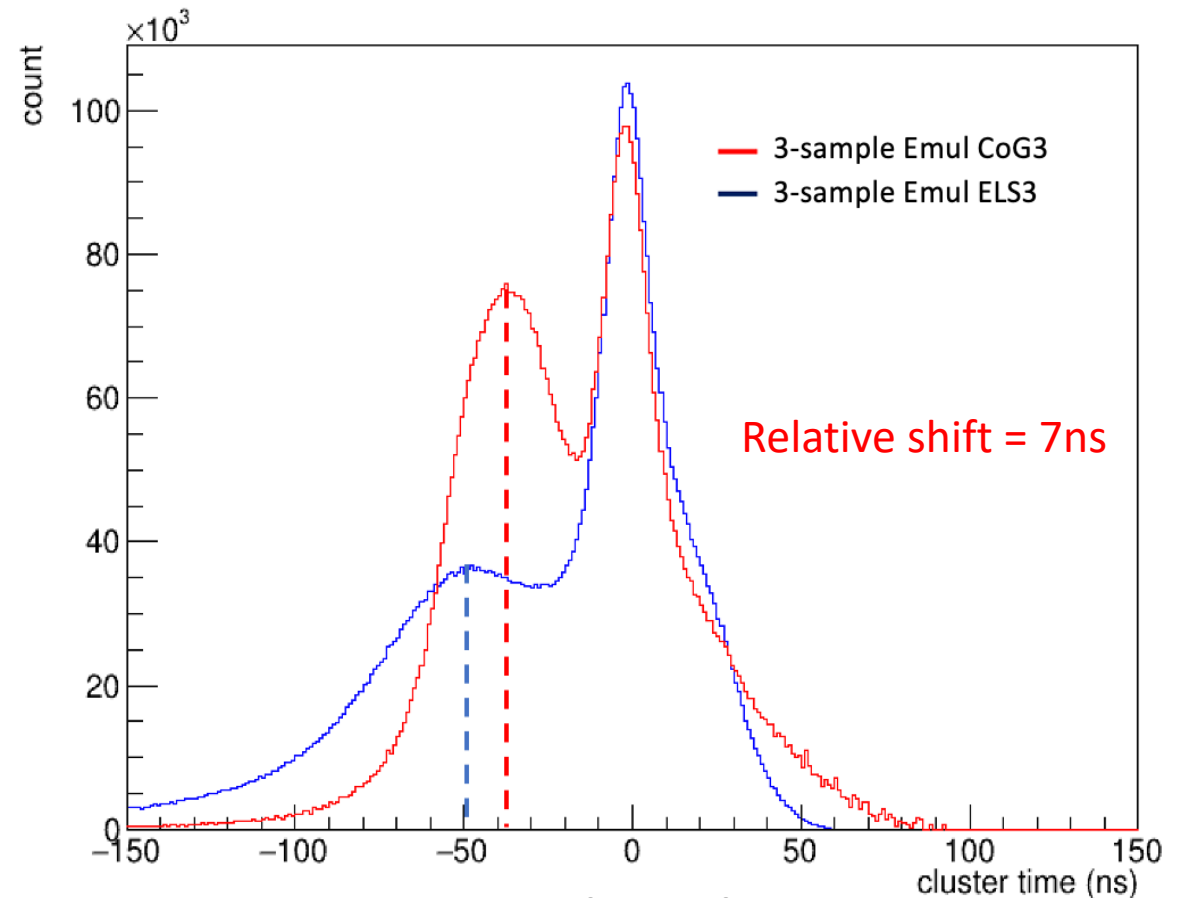
SVD U-Cluster Time in FTSW reference for layer 3 sensors ~ Exp21 Run234



6-sample

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SVD U-Cluster Time in FTSW reference for layer 3 sensors ~ Exp21 Run234



3-sample emulation

ROC

(Receiver Operating Characteristic)

Parameter settings

- Using **ROC curve** to compare the performance of **4 different cases** (CoG3 & ELS3 6-sample, CoG3 & ELS3 3-sample) with different cluster time threshold cuts:

- **Define variables**

- S_{total} = total # of signal hits (no constraints)
- B_{total} = total # of background hits (no constraints)
- S_{sel} = # of signal hits selected within certain time cut
- B_{sel} = # of bkg hits selected within certain time cut

Need to fit the cluster time plot to get these parameter values

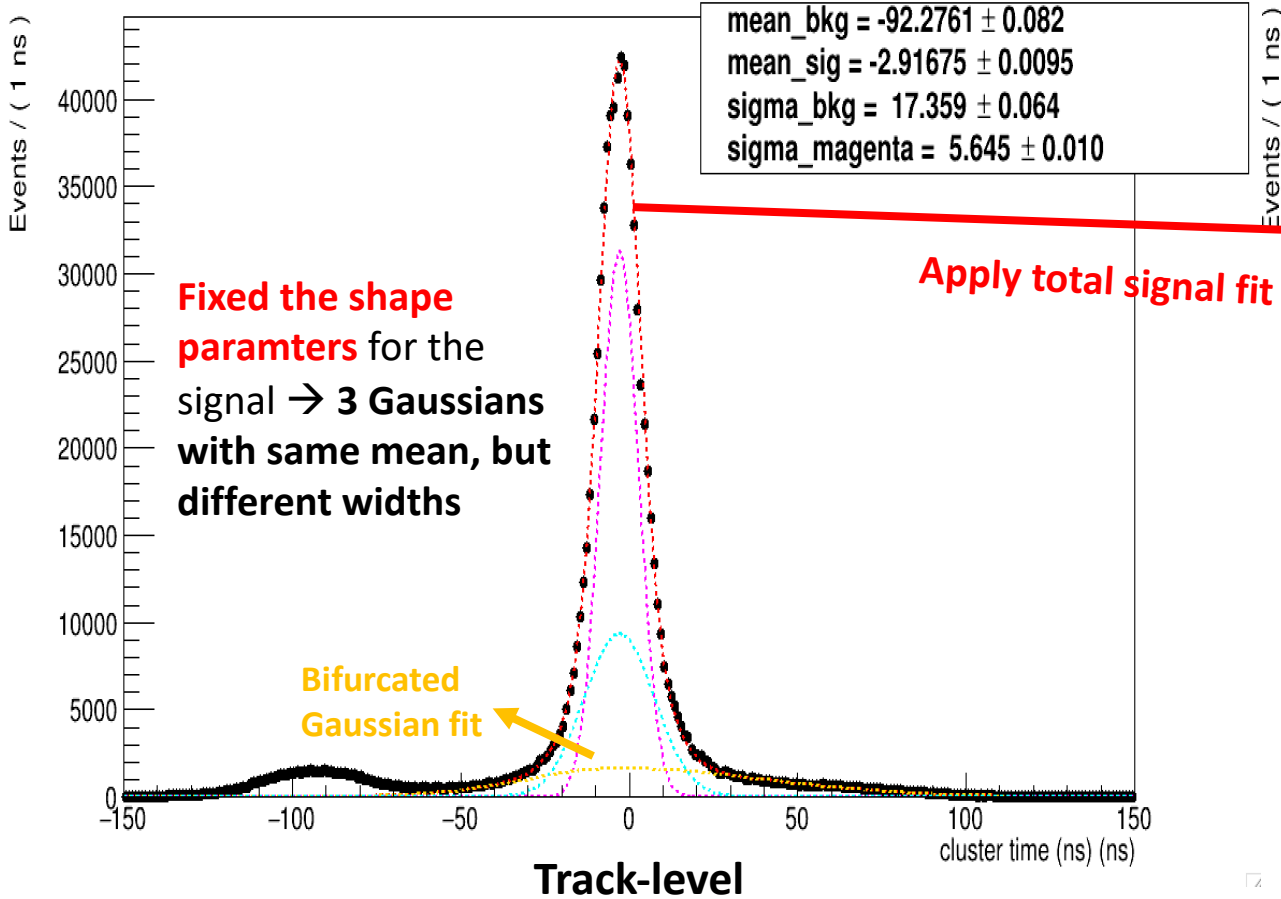
- **For different time cuts:**

- $S_{eff} = \frac{S_{sel}}{S_{total}}$
- $B_{rej} = 1 - \frac{B_{sel}}{B_{total}}$
- $Purity = \frac{S_{sel}}{S_{sel} + B_{sel}}$
- Build S_{eff} vs B_{rej} & $Purity$ vs S_{eff} curves

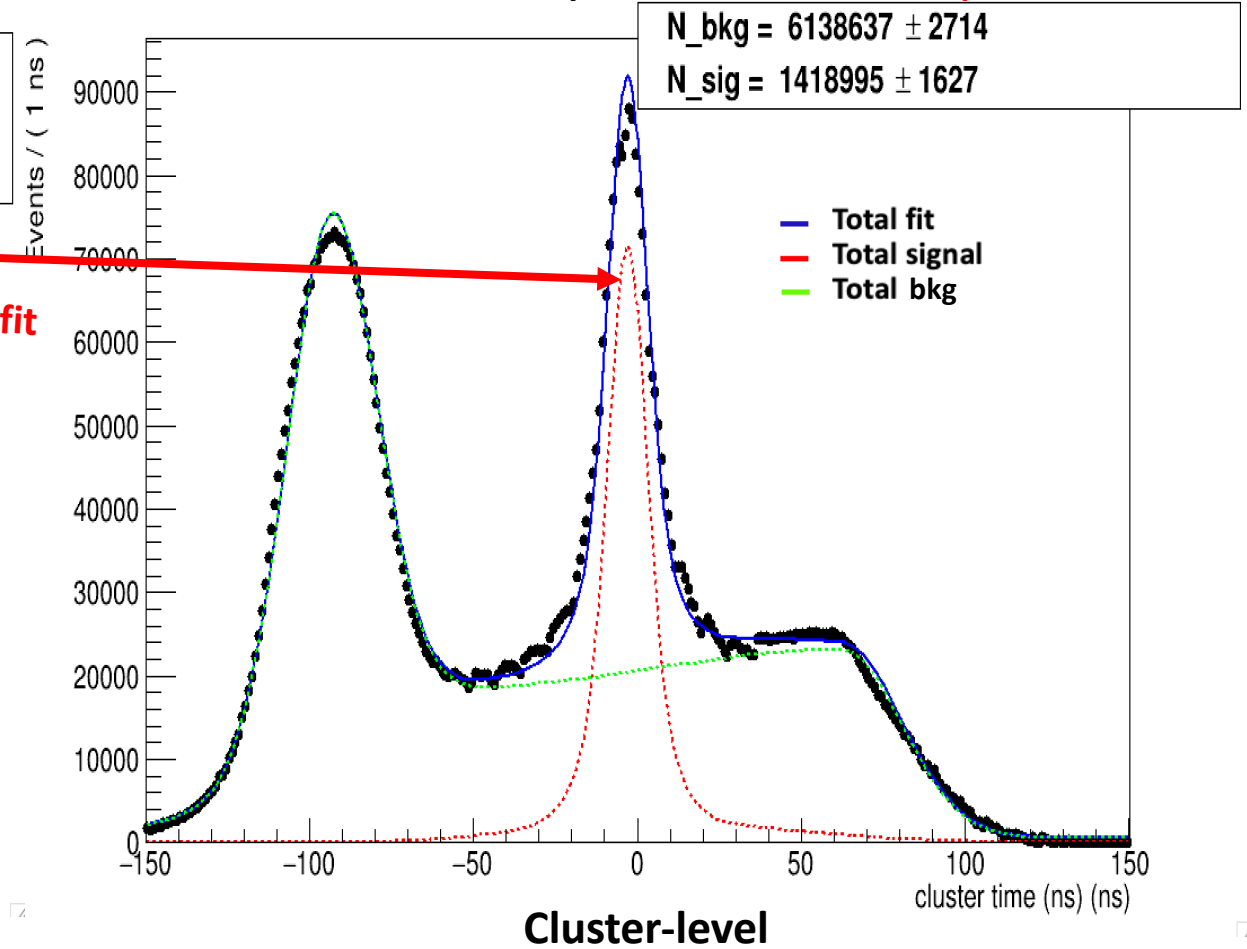
CoG3 6-sample cluster time fit

*Same method to fit other three cases. Tune on the parameter.

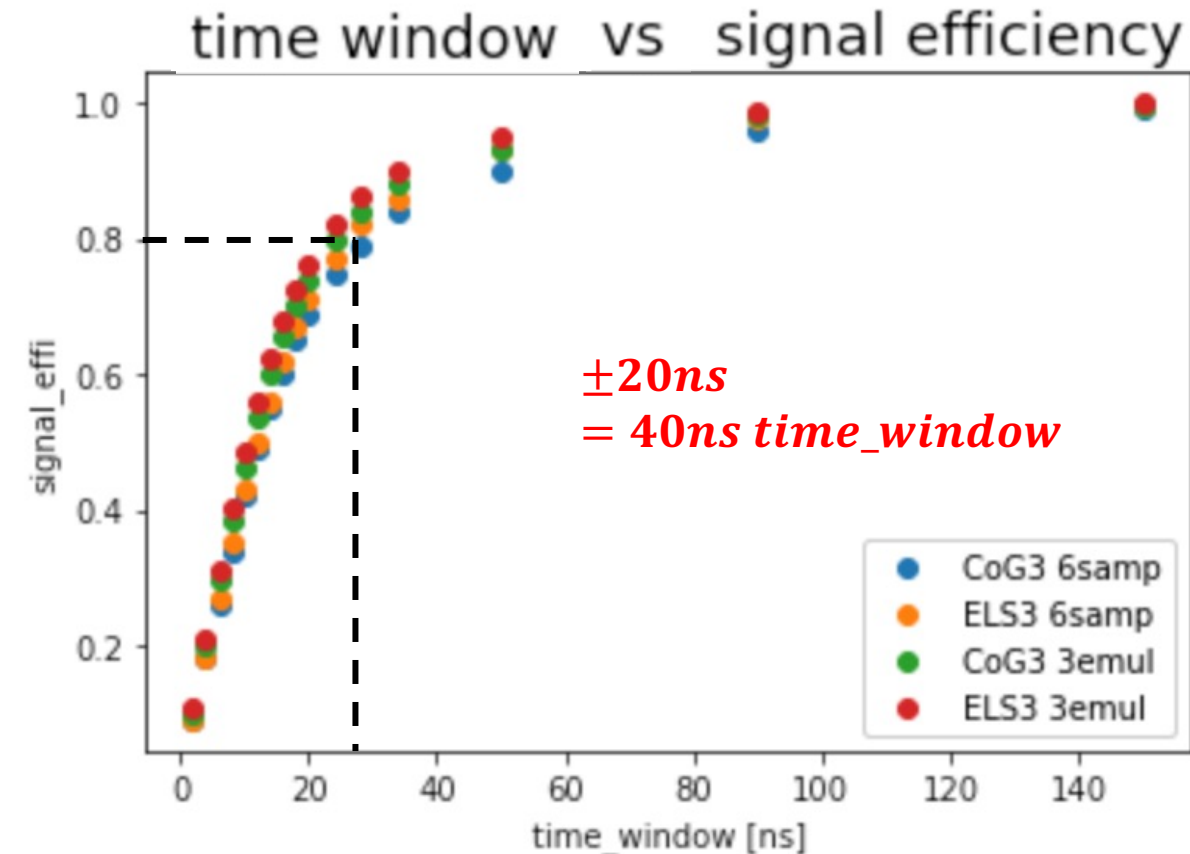
SVD U-Cluster-on-Track Time for layer 3 sensors **CoG3 6-Sample**



SVD U-Cluster Time for layer 3 sensors **CoG3 6-sample**

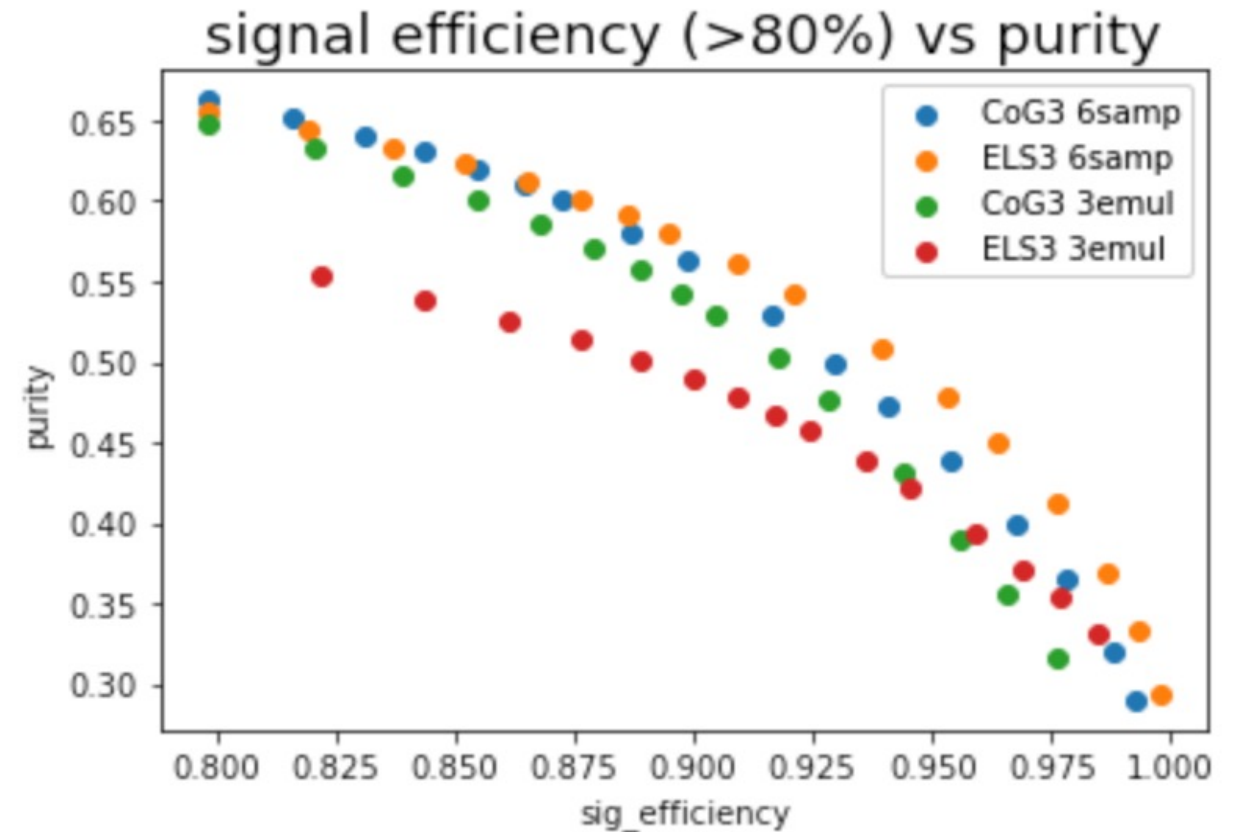
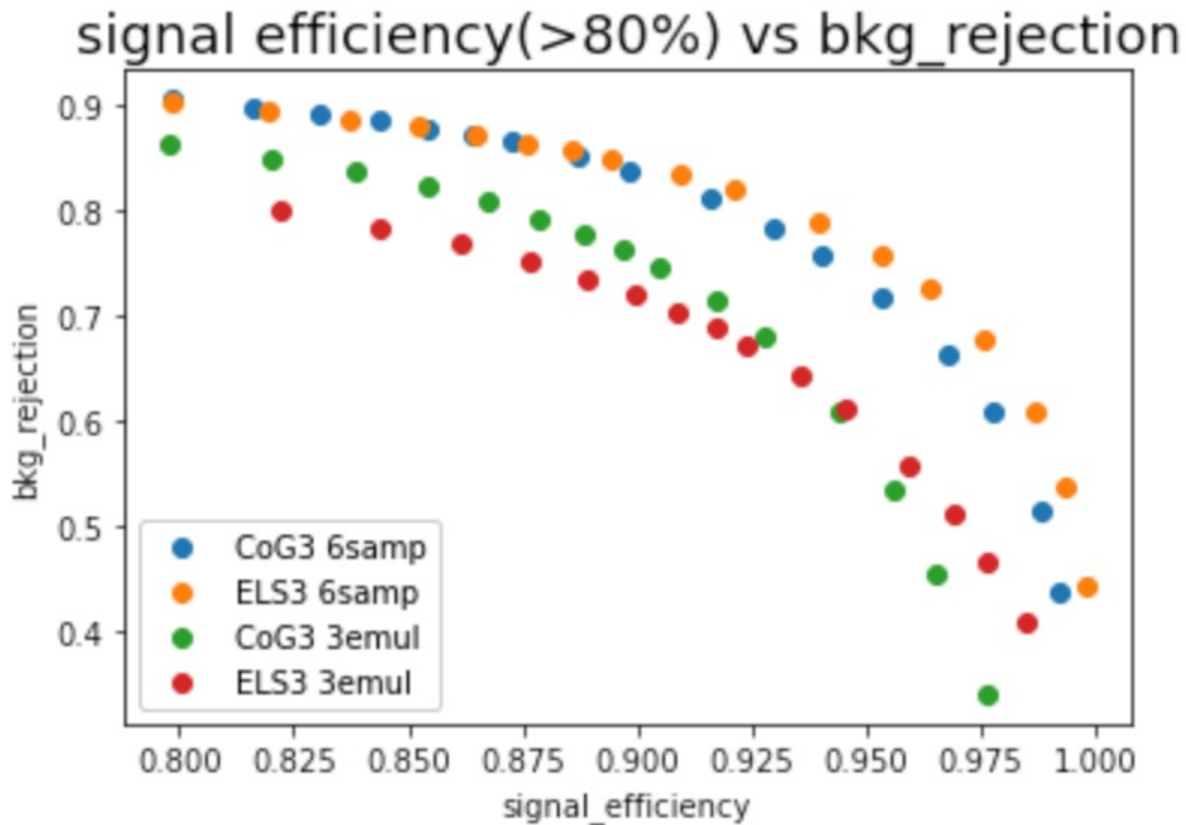


General time window scan



- General time window scan:
 - From 0 ns to 150 ns
- ROC curve is roughly the same for four different cases
 - Similar signal distribution
- Physics analysis usually focus on **high signal efficiency ($> 80\%$)**
 - Time window $\sim 28 \text{ ns}$ ($\pm 14 \text{ ns}$)

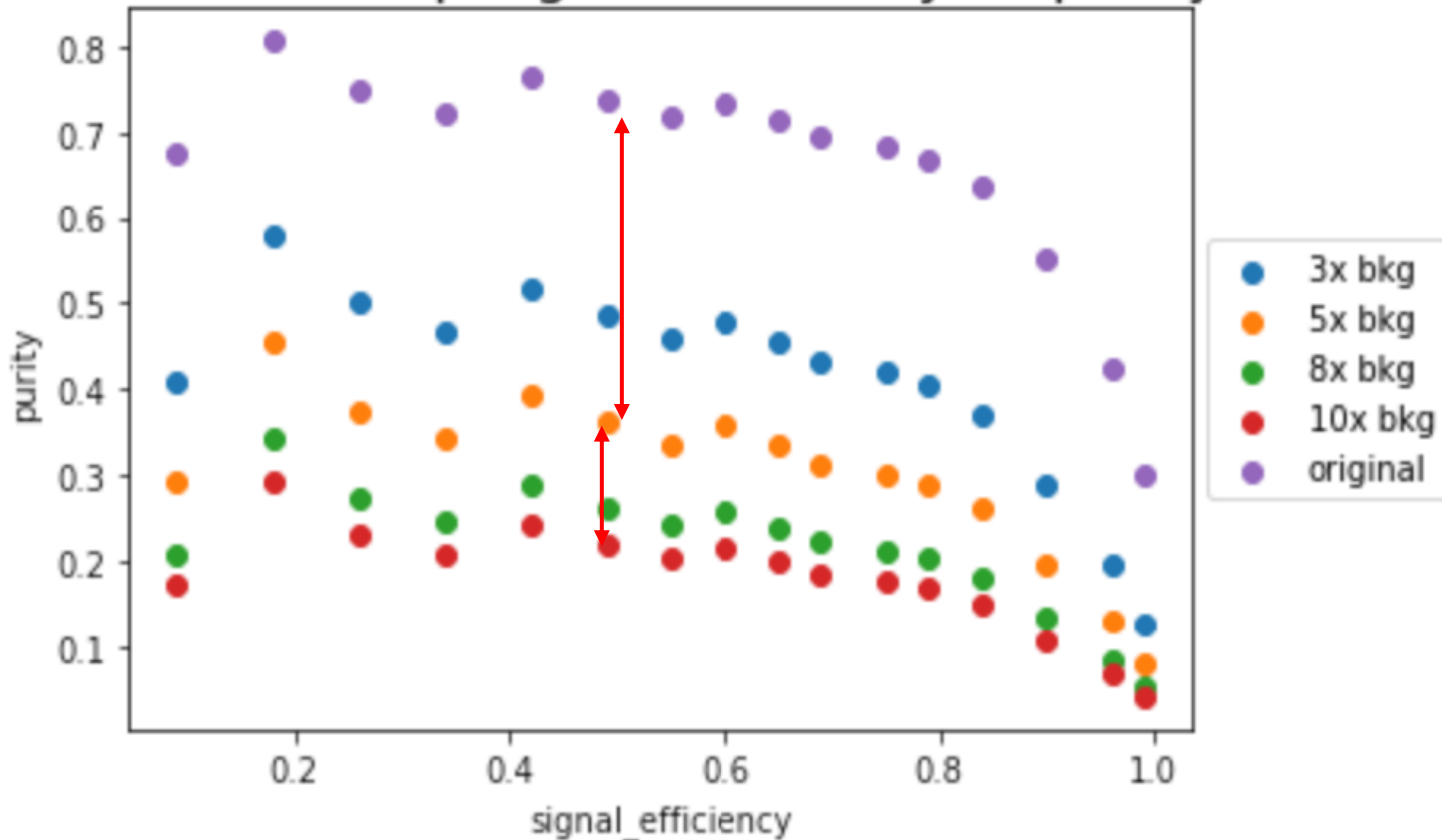
ROC curve: high signal efficiency



- For B_{rej} : 6-sample is better than 3-sample
- For $purity$: 6, 3-sample perform about the same at high S_{eff}

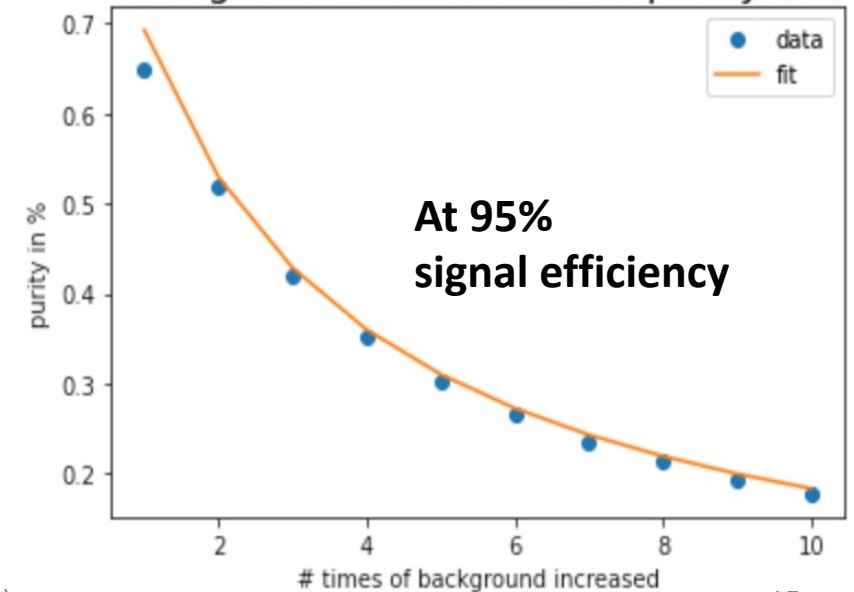
S_efficiency vs Purity with increasing bkg

CoG3 6samp signal efficiency vs purity



- **Purity is very low at high signal efficiency** → need better cut selection

background coefficient vs. purity (%)

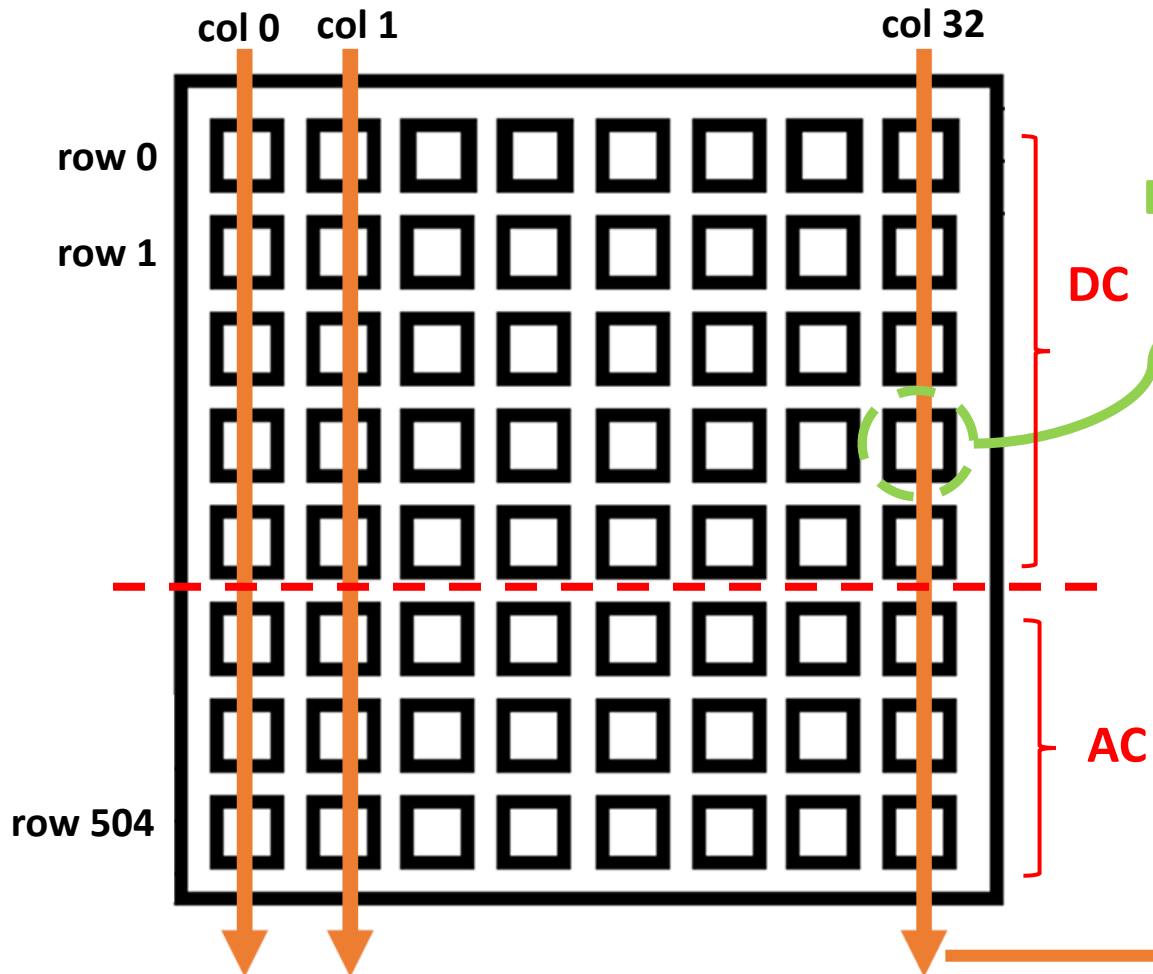


CMOS Sensor

(Complementary Metal Oxide Semiconductor)

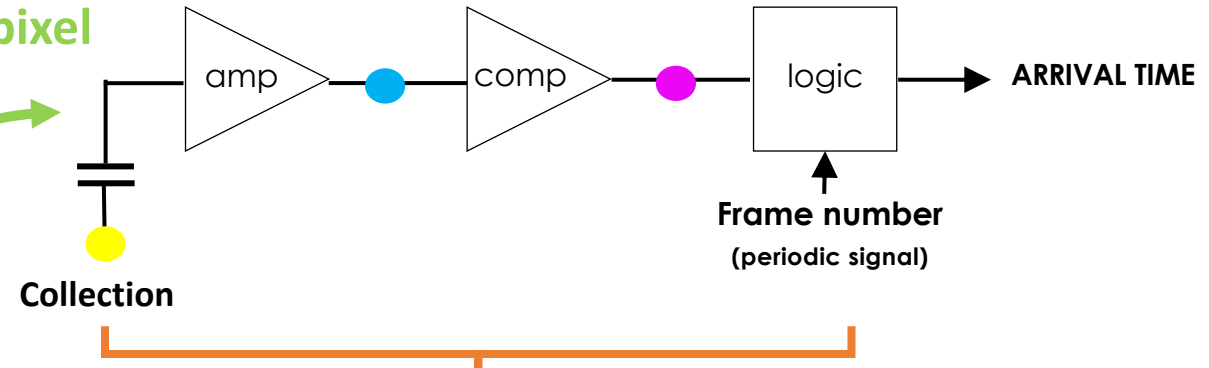
Basic MIMOSIS-Fast architecture

Pixel Matrix



Pixel size: $27 \times 30 \mu m^2$
Thickness: $50 \mu m$

Each pixel

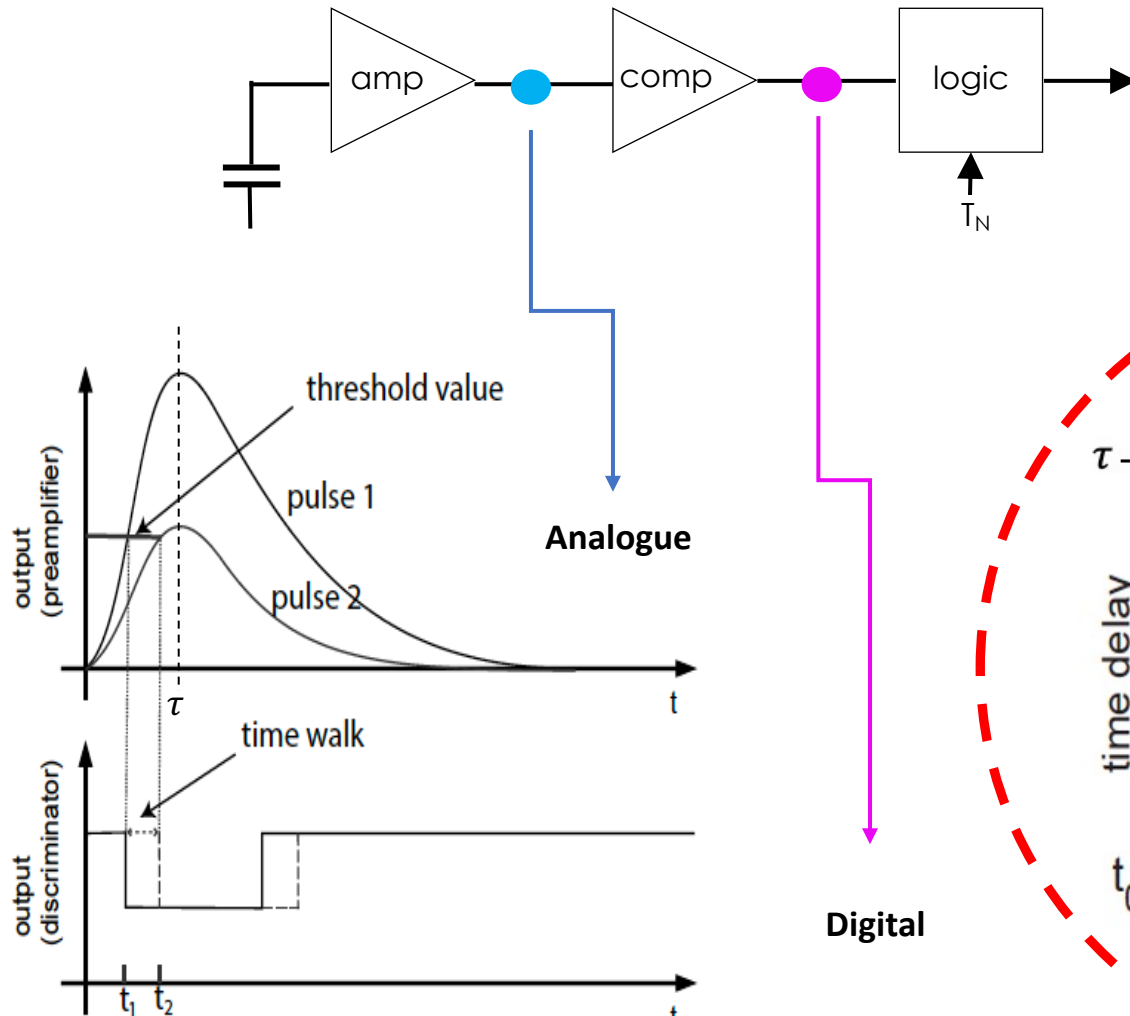


Integrated circuit: **Collection + amplifier + comparator**

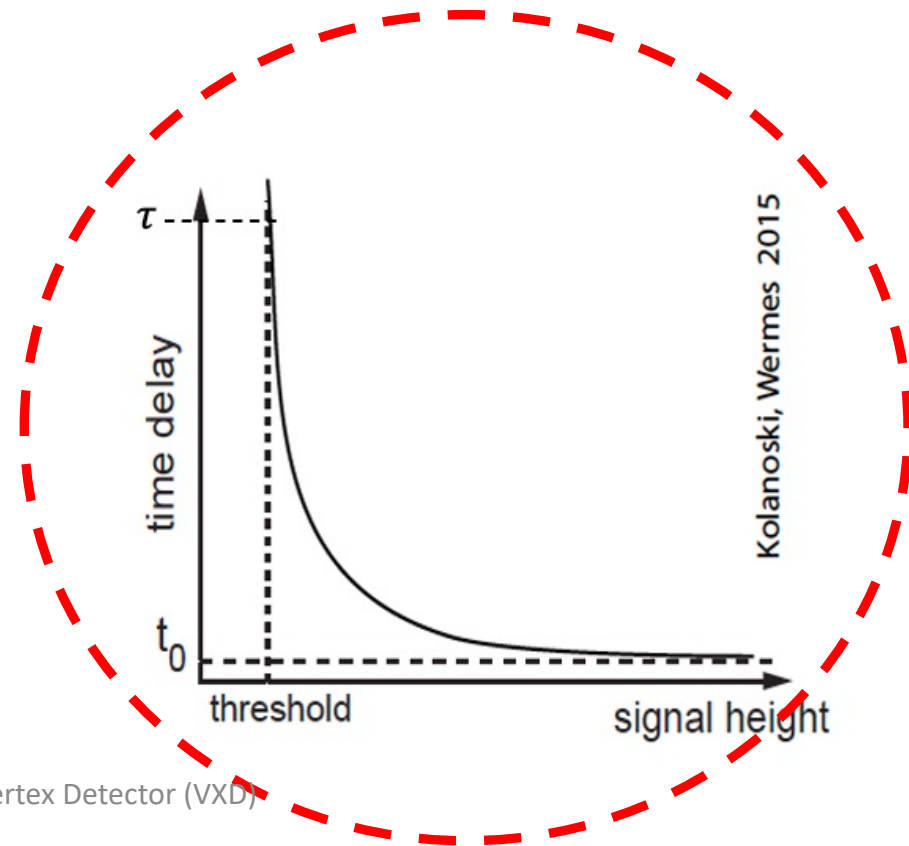
Very Fast !!!

Data driven read-out

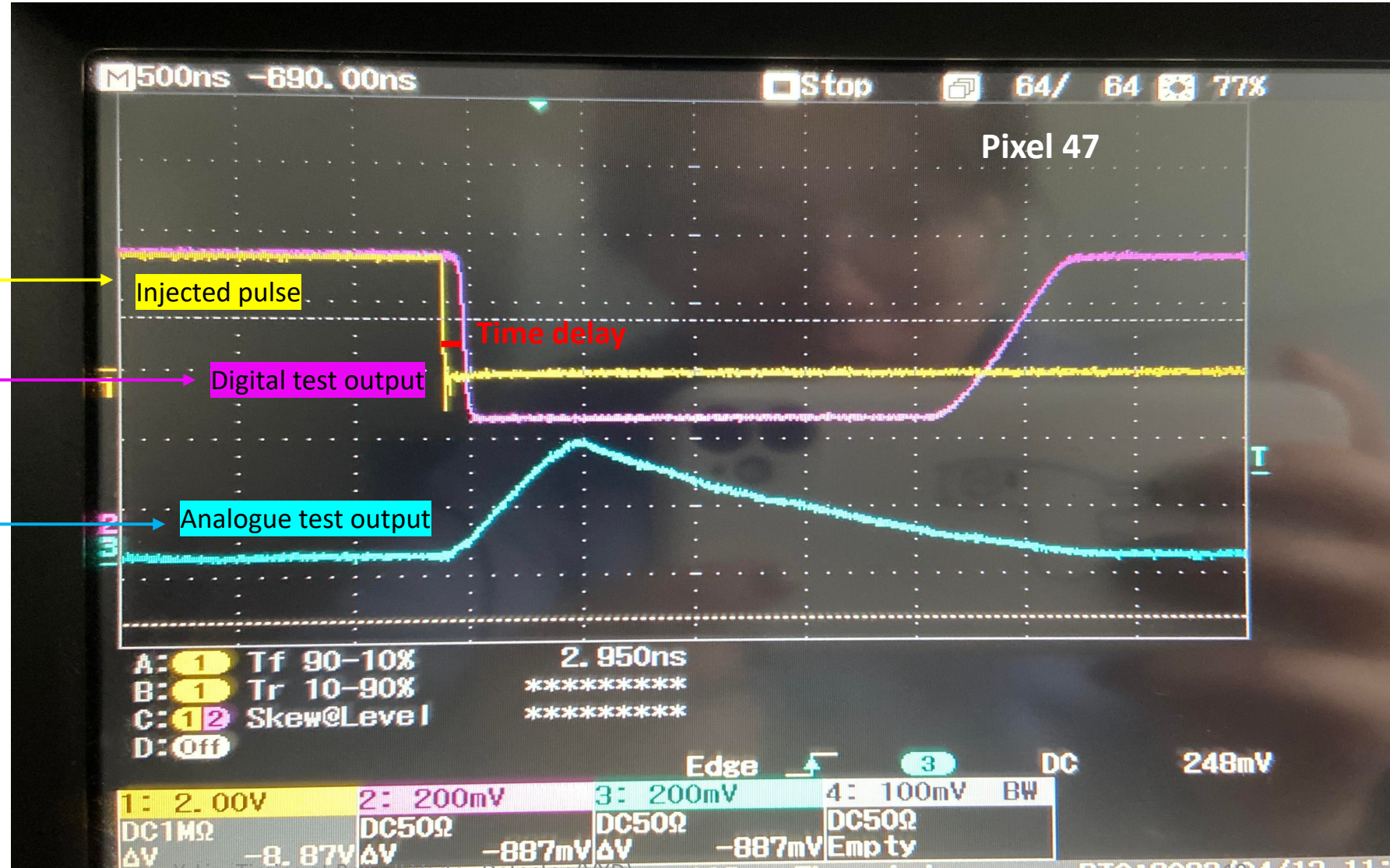
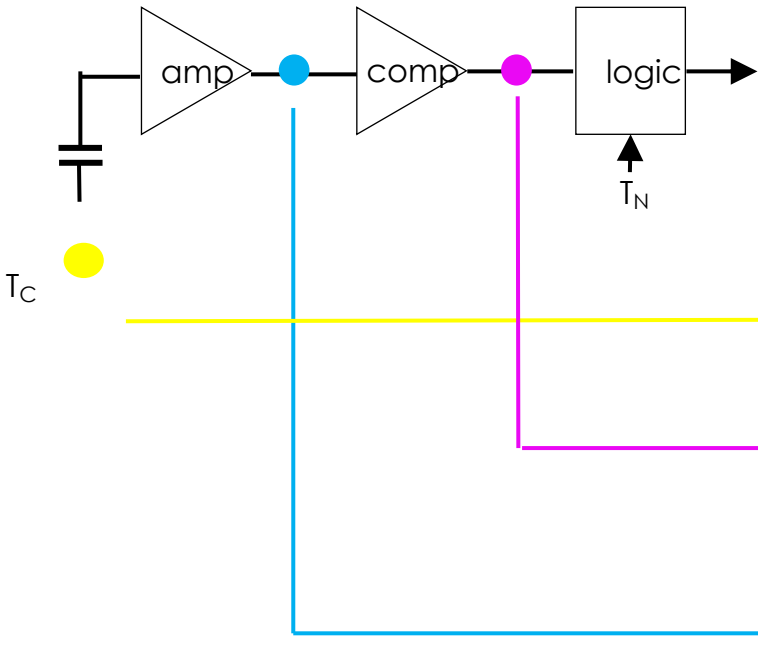
Time walk



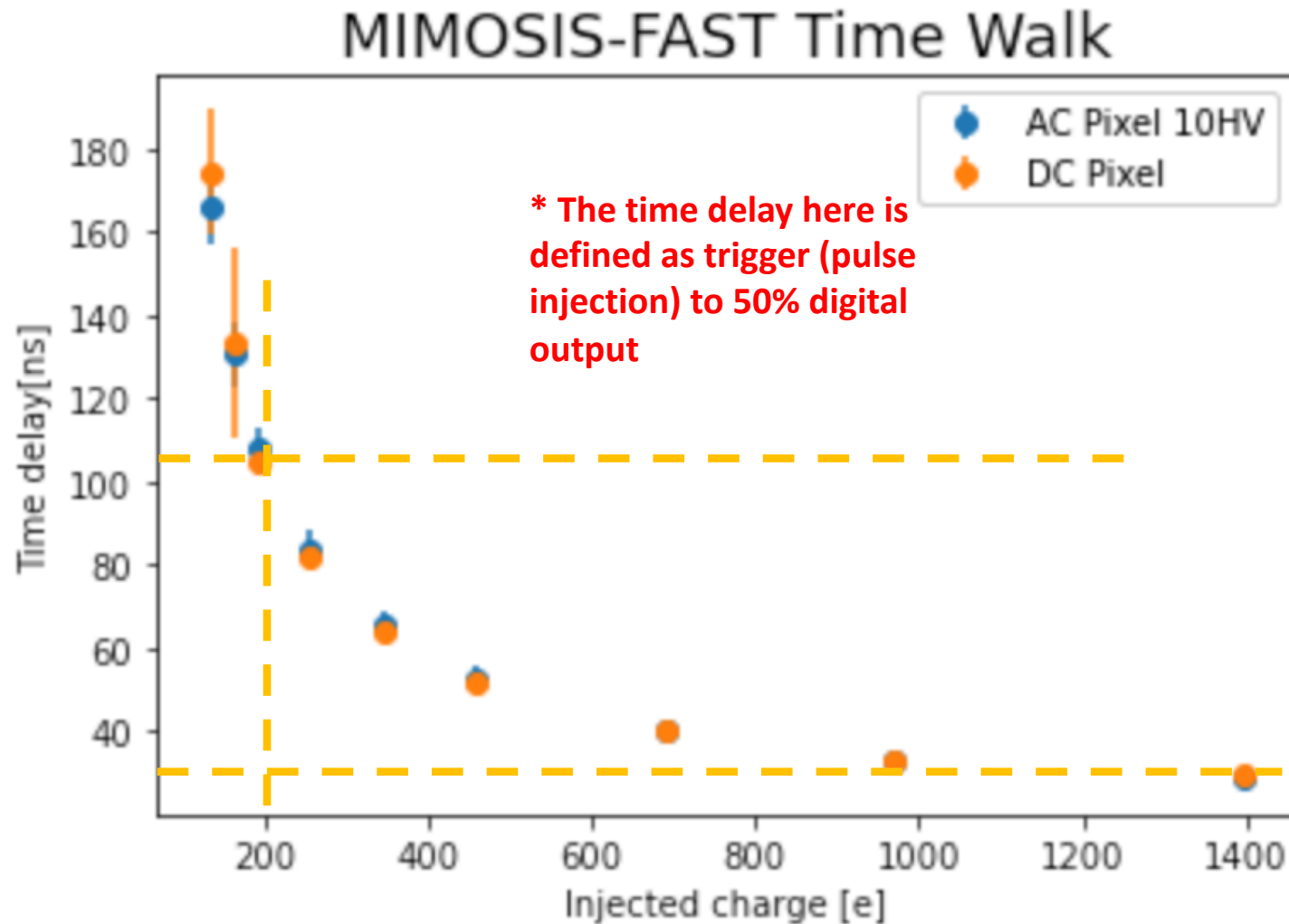
Time delay depends on the different amount of charges



Oscilloscope output



MIMOSIS-Fast time walk



- Average values of the DC, AC pixels
- **No difference in the DC & AC pixels:**
 - ~30ns at 1400 e charges
 - **Time walk:** 75 ns from 200 e to 1400 e charges
- Test only electronic behaviors with injected charges. Further test on ionization charges needed.

Summary

- **The high-luminosity anticipated at Belle-II will create high occupancy in the future**
- Simple cut down on the readout sample gives worse purity & bkg rejection.
 - **Machine learning algorithms are currently under development**
- The charge injection only tests the electronics behavior of the CMOS sensor (**~75ns time from 200 e ~ 1400 e charges**)
 - **Laser with precise time of arrival to test the ionisation charge collection time**

Back-up

Beam induced backgrounds

- Single beam effects

- **Touschek** ☐ intra-beam scattering

- rate $\propto \frac{I_{bunch}^2 N_{bunch}}{(\sigma_x \sigma_y) E_{beam}^3} = \frac{I_{beam}^2}{(\sigma_x \sigma_y) E_{beam}^3 N_{bunch}}$

- **Beam gas** ☐ vacuum residues

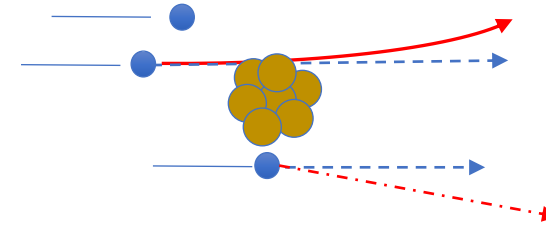
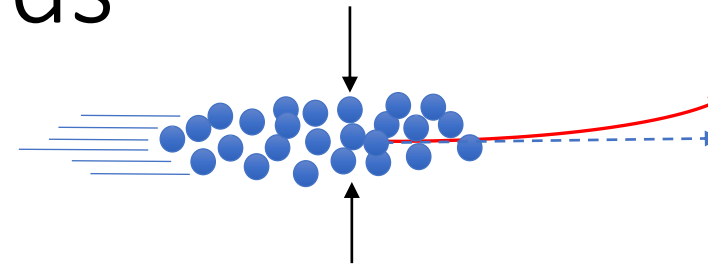
- rate $\propto I_{bunch} \times N_{bunch} \times P(I)$
 - Dynamic pressure $P(I) = (p_0 + p_1 I_{beam})$

- **Synchrotron radiation** ☐ magnet bending

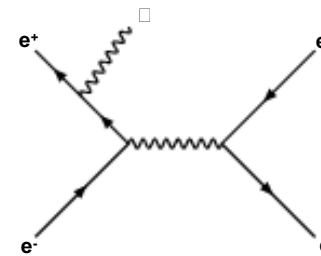
- rate $\propto I_{beam}$

- Beam-beam effects (QED)

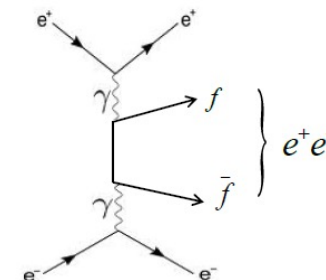
- rate \propto Luminosity



Slide taken from J. Baudot



Radiative Bhabha scattering

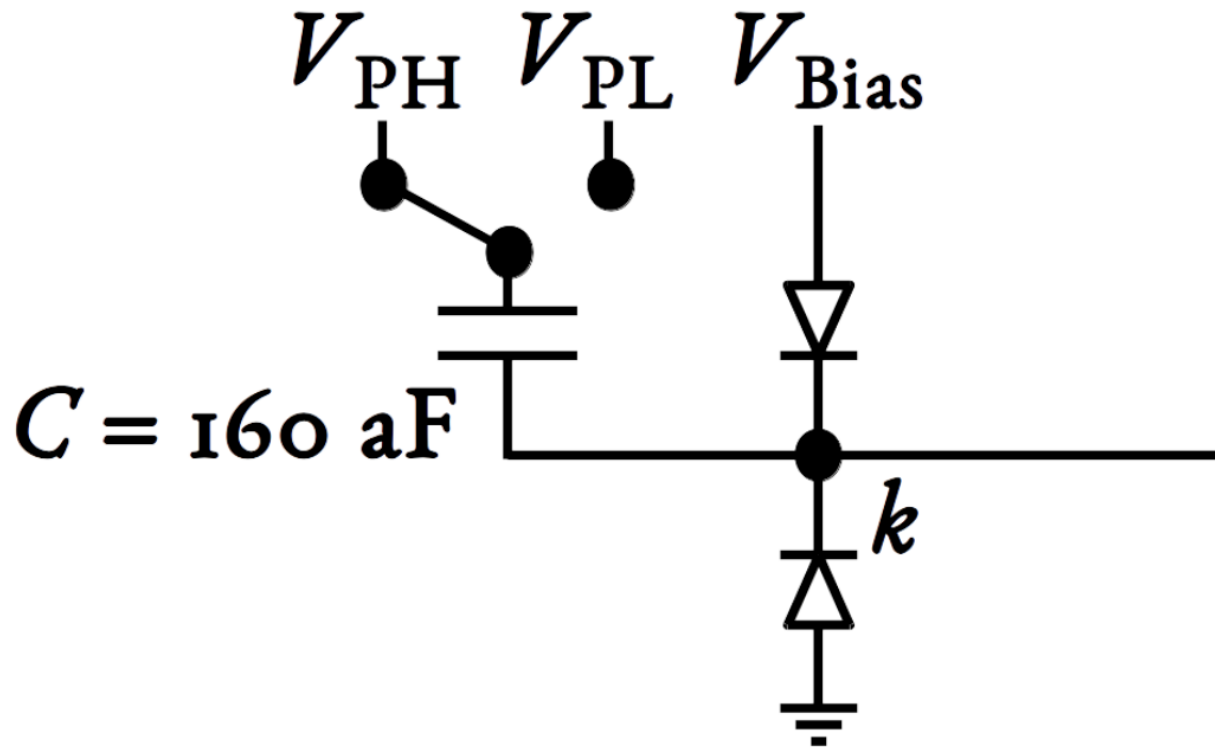


2-photon interaction

VTX upgrade

- Replacing the whole VXD with a new vertex detector (VTX), composed with 5-layers of **Monolithic Active Pixel Sensors (MAPS)** based on the **CMOS technology**
- The occupancy level with VTX is expected to be below $1e^{-4}$ in any background level conditions.
- The proposed MAPS has a **25 to 100ns integration time**

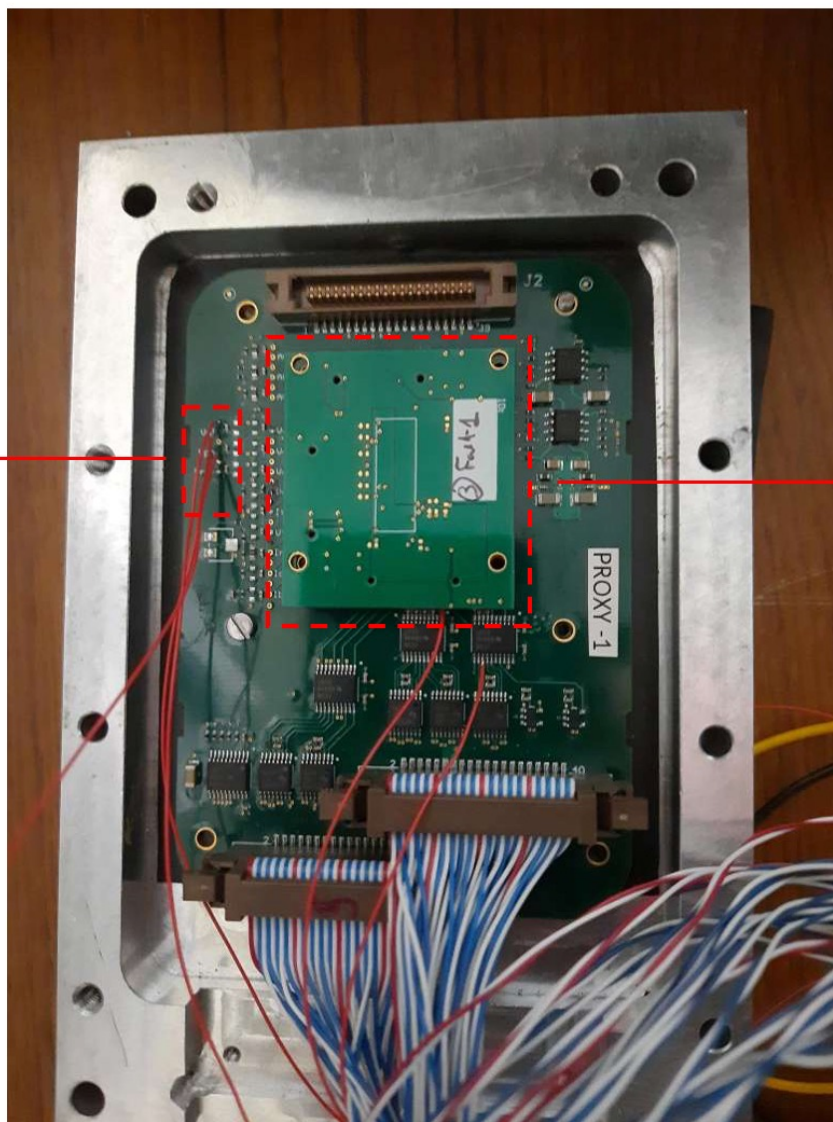
Charge injection



- The injected voltage is first set to V_{PL} with V_{Bias} set to the working voltage of a diode.
- Once the charge is injected, the injection voltage will be set to V_{PH} .
- The quick change of voltages induces the charge to the node k with $Q = C \cdot (V_{PH} - V_{PL})$.
- The capacitance is set to be 160aF so that 1mV voltage difference corresponds to 1e charge generated on the electrodes

Proxy board

**VPulseHigh &
VPulseLow test
connection output**



MIMOSIS-Fast chip